RELIABILITY REPORT

FOR

MAX6778XK+

PLASTIC ENCAPSULATED DEVICES

December 1, 2011

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX6778XK+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX6775-MAX6781 low-power, 1%-accurate battery monitors are available in the ultra-small µDFN package (1.0mm x 1.5mm) and SC70 packages. These low-power devices are ideal for monitoring single lithium-ion (Li+) cells, or multicell alkaline/NiCd/NiMH power sources. These devices offer single (MAX6775/MAX6776/MAX6777/MAX6778) or dual (MAX6779/MAX6780/MAX6781) low-battery outputs and feature fixed or resistor-adjustable hysteresis. Hysteresis eliminates the output chatter sometimes associated with battery voltage monitors, usually due to input-voltage noise or battery terminal voltage recovery after load removal. These devices are available in several versions: with single- or dual-voltage monitors, and with fixed or adjustable hysteresis. The MAX6775/MAX6776 offer a single battery monitor and factory-set hysteresis of 0.5%, 5%, or 10%. The MAX6779/MAX6780/MAX6781 have two battery monitors in a single package and factory-set hysteresis of 0.5%, 5%, or 10%. The MAX6777/MAX6778 offer a single battery monitor with external inputs for the rising and falling thresholds, allowing external hysteresis control. For convenient interface with system power circuitry or microprocessors, both open-drain and push-pull outputs are available. The single-channel devices are available with open-drain or push-pull outputs. The dual-channel devices are available with both outputs open-drain, both outputs push-pull, or one of each (see the *Selector Guide* in the full data sheet). This family of devices is offered in small 5-pin SC70 and ultra-small 6-pin µDFN packages, and is fully specified over the -40°C to +85°C extended temperature range.

II. Manufacturing Information

A. Description/Function:	Low-Power, 1%-Accurate Battery Monitor in µDFN and SC70 Packages
B. Process:	C6
C. Number of Device Transistors:	496
D. Fabrication Location:	California
E. Assembly Location:	Texas, Thailand
F. Date of Initial Production:	October 22, 2005

III. Packaging Information

A. Package Type:	5L SC70
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1856 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	324°C/W
K. Single Layer Theta Jc:	115°C/W
L. Multi Layer Theta Ja:	324°C/W
M. Multi Layer Theta Jc:	115°C/W

IV. Die Information

A. Dimensions:	31 X 30 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 45 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 24.4 \times 10^{-9}$

$\lambda = 24.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the C6 Process results in a FIT Rate of 0.43 @ 25C and 7.50 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SUVDAQ001C D/C 0540)

The MS90-3 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX6778XK+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0	S0000Q109C, D/C 0525

Note 1: Life Test Data may represent plastic DIP qualification lots.